



N-Channel 20 V (D-S) MOSFET

PRODU	PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)	Q _g (Typ.)			
20	0.020 at V _{GS} = 4.5 V	6.5	10			
20	0.025 at V _{GS} = 2.5 V	4.6	10			

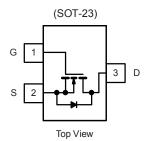
FEATURES

• TrenchFET® Power MOSFET

APPLICATIONS

- · Load Switching for Portable Devices
- DC/DC Converter





ABSOLUTE MAXIMUM RATINGS ((T _A = 25 °C, unle	ess otherwise	noted)		
Parameter		Symbol	5 s	Steady State	Unit
Drain-Source Voltage		V _{DS}	20		V
Gate-Source Voltage		V_{GS}	± 8		
Continuous Drain Comment /T = 450 °C)	T _A = 25 °C	- I _D	6.5	4.6	
Continuous Drain Current (T _J = 150 °C) ^a	T _A = 70 °C		5.2	3.1	
Pulsed Drain Current ^b		I _{DM}	30		Α
Continuous Source Current (Diode Conduction) ^a		I _S	0.92	0.7	
Daniel Birating	T _A = 25 °C	P _D	1.46	0.85	W
Power Dissipation ^a	T _A = 70 °C		0.95	0.57	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150		°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Marrian Institut to Ambient	t ≤ 5 s	R_{thJA}	70	95	°C/W
Maximum Junction-to-Ambient ^a	Steady State	'`thJA	100	125	
Maximum Junction-to-Foot	Steady State	R_{thJF}	62	78	

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. Pulse width limited by maximum junction temperature.



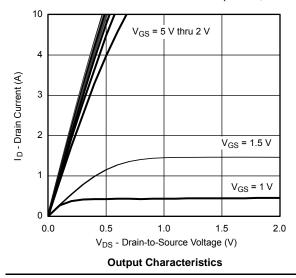
			Limits				
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V_{DS}	V_{GS} = 0 V, I_D = 250 μA	20			V	
Gate-Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.40		1.5	V	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 8 V			± 100	nA	
		V _{DS} = 20 V, V _{GS} = 0 V			0.1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 20 V, V _{GS} = 0 V, T _J = 50 °C			4	μA	
	-	V _{DS} = 20 V, V _{GS} = 0 V, T _J = 70 °C			15		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, V_{GS} = 4.5 \text{ V}$	30			Α	
5 . 6 . 6 3	В	V _{GS} = 4.5 V, I _D = 2.6 A		0.020	0.022	0	
Drain-Source On-Resistance ^a	R _{DS(on)}	V _{GS} = 2.5 V, I _D = 1.6 A		0.025	0.027	Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 5 V, I _D = 3.6 A		13		S	
Diode Forward Voltage	V_{SD}	I _S = 0.95 A, V _{GS} = 0 V		0.7	1.2	V	
Dynamic ^b			•				
Total Gate Charge	Q_g			3.5	5.5		
Gate-Source Charge	Q_{gs}	V_{DS} = 10 V, V_{GS} = 4.5 V, I_{D} = 3.6 A		0.6		nC	
Gate-Drain Charge	Q _{gd}			0.45			
Gate Resistance	R_g	f = 1 MHz	2	4	8	Ω	
Switching			•				
Turn-On Delay Time	t _{d(on)}			8	15		
Rise Time	t _r	V_{DD} = 10 V, R_L = 2.78 Ω		7	15	ns	
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D}\cong 3.6$ A, V_GEN = 4.5 V, R_g = 1 Ω		30	45		
Fall Time t _f				7	15	1	
Source-Drain Reverse Recovery Time	t _{rr}	L = 2.6 A dl/dt = 100 A/:		8.5	15		
Body Diode Reverse Recovery Charge	Q _{rr}	$I_F = 3.6 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}$		2	4	nC	

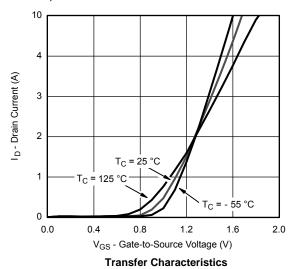
Notes:

- a. Pulse test: Pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

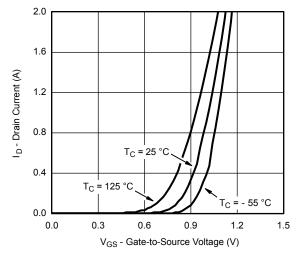
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



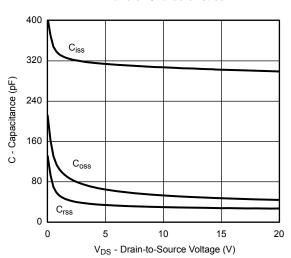




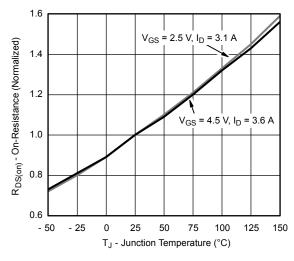
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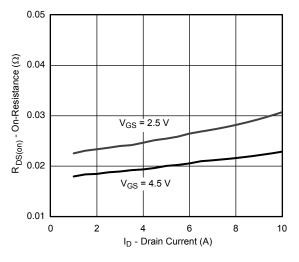
Transfer Characteristics



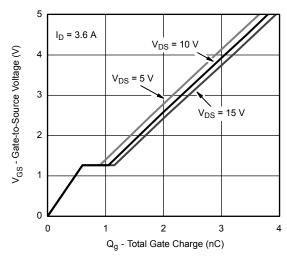
Capacitance



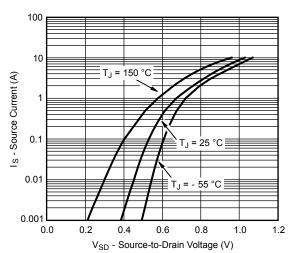
On-Resistance vs. Junction Temperature



On-Resistance vs. Drain Current



Gate Charge

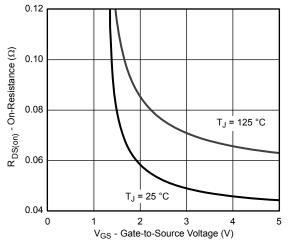


Source-Drain Diode Forward Voltage

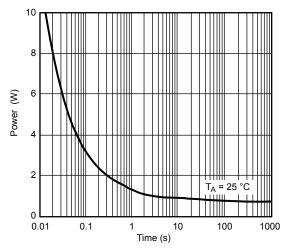




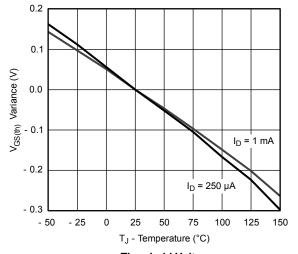
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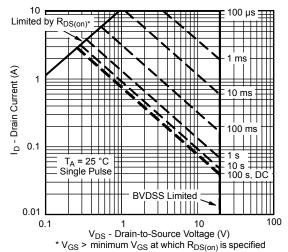
On-Resistance vs. Gate-to-Source Voltage



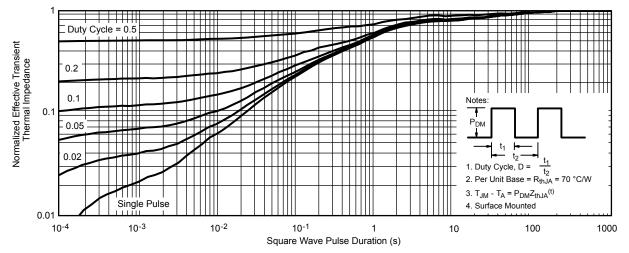
Single Pulse Power



Threshold Voltage

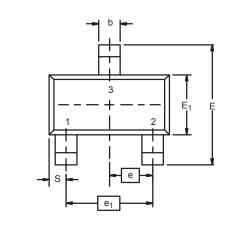


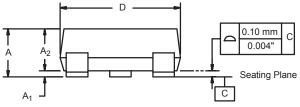
Safe Operating Area, Junction-to-Ambient

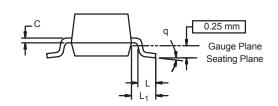


Normalized Thermal Transient Impedance, Junction-to-Ambient

SOT-23: 3-LEAD





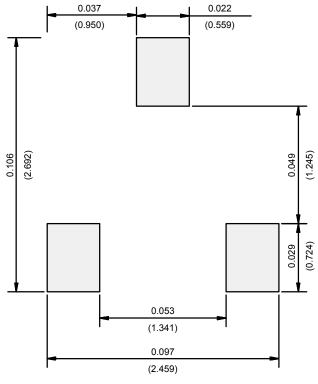


Dim	MILLIN	IETERS	INCHES			
	Min	Max	Min	Max		
Α	0.89	1.12	0.035	0.044		
A ₁	0.01	0.10	0.0004	0.004		
A ₂	0.88	1.02	0.0346	0.040		
b	0.35	0.50	0.014	0.020		
С	0.085	0.18	0.003	0.007		
D	2.80	3.04	0.110	0.120		
E	2.10	2.64	0.083	0.104		
E ₁	1.20	1.40	0.047	0.055		
е	0.95 BSC		0.0374 Ref			
e ₁	1.90 BSC		0.074	0.0748 Ref		
L	0.40	0.60	0.016	0.024		
L ₁	0.64 Ref		0.025	Ref		
S	0.50 Ref		0.020	Ref		
q	3°	8°	3°	8°		

ECN: S-03946-Rev. K, 09-Jul-01

DWG: 5479

RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)





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